IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re th	ne application of:	
	Hung-Chin Guthrie et al.	Group Art Unit: Unassigned
Annlia		Examiner: Unassigned
Аррис	eation No. Unassigned	Atty. Docket No. HIT1P057/
Filed:	Herewith) HSJ920030250US1)
For:	ONE STEP COPPER DAMASCENE CMP PROCESS AND SLURRY	Date: February 27, 2004)
		1

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450 with label number EV395032358US on Eepruaty 27, 2004.

gned:

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR §§ 1.56 AND 1.97(b)

Mail Stop Patent Application Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of which are attached, may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§ 1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is believed to be filed before the mailing date of a first Office Action on the merits. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 50-2587 (Order No. <u>HSJ920030250US1/HIT1P057</u>).

Respectfully submitted,

Silicon Valley P Group, PC

Ronald B. Feece Reg. No. 46,327

P.O. Box 721120

San Jose, CA 95172-1120

Telephone: (408) 971-2573

Form 1449 (Modified)	Atty. Docket No.	Application No.:
	HIT1P057/	Unassigned
	HSJ920030250US1	-
Information Disclosure	Applicant:	
Statement By Applicant	Guthrie et al.	
	Filing Date:	Group Art Unit:
(Use Several Sheets if Necessary)	Herewith	Unassigned

U.S. Patent Documents

Examiner						Sub-	Filing
Initial	No.	Patent No.	Date	Patentee	Class	class	Date
	1	2003/0184912	10/02/2003	Hsiao et al.	360	123	04/02/2002
	2	2003/0135986	07/24/2003	Eschbach et al.	29	603.12	01/14/2002
	3	2003/0104770	06/05/2003	Pasqualoni et al.	451	60	04/30/2001
	4	2003/0104699	06/05/2003	Minamihaba et al.	438	692	11/26/2002.
	5	2003/0079416	05/01/2003	Ma et al.	51	307	08/17/2001
	6	6,554,878	04/29/2003	Dill, Jr. et al.	51	308	06/14/1999
	7	6,510,022	01/21/2003	Lahiri et al.	360	126	02/15/2000
_	8	6,508,953	01/21/2003	Li et al.	252	79.1	10/19/2000
	9	2002/0191336	12/19/2002	Hsiao et al.	360	126	06/18/2001
	10	6,468,913	10/22/2002	Pasqualoni et al.	438	693	07/08/2000
	11	2002/0016275	02/07/2002	Yano et al.	510	254	06/29/2001
	12	6,226,149	05/01/2001	Dill, Jr. et al.	360	126	12/15/1998
	13	6,195,872	03/06/2001	Sasaki	29	603.13	06/01/1998
	14						
	15						
	16						
	17						

Foreign Patent or Published Foreign Patent Application

Examiner		Document	Publication	Country or	Ţ	Sub-	Trans	lation
Initial	No.	No.	Date	Patent Office	Class	class	Yes	No
	18	2003100678	2003-04-04	JР	H01L	21/304		
	19	2001031953	2001-02-06	JР	C09K	3/14		

Other Documents

Examiner		
Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	20	Yoshimizu, H., et al., "Thin Film Magnetic Film Head Composed of Inorganic Materials," IEEE Transactions on Magnetics, Volume 28, No. 5, September 1992
	21	"Alkaline Formulations for Chemical Mechanical Polishing of Copper Utilizing Azole Passivation", IBM Technical Disclosure Bulletin, October 1994
	22	"Chemical-Mechanical Polishing of Copper with Ammonium Persulfate", IBM Technical Disclosure Bulletin, October 1994
	23	
Examiner		Date Considered
L		

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.